

D.P.A.E-Certa, Inc. Internal Visual Verification Analysis

Client	Western Electronics Distribution				
DPA/W.O.#	ECDPA33				
Part Identification	S5935QF				
Manufacturer	AMC CAPS				
P.O. #	11859				
Date Code	5				
Quantity	1				
Package Type	QFP				

Lot Disposition

Submitted By:	_x_ Meets Requirements
Reviewed By: SE	Does Not Meet Requirements
Approved By: Joel Deutsch	_x_ Customer Review



8-5-09

Laboratory Summary

Analysis Procedure/Results:

Meets requirements. Texas Instrument name "Ti" is present on die.

Inspection Performed per: Mil-Std 883 Method 2013 Discrepancies: ___Yes _x_No

Sample #	1					
Anomaly						
Anomaly						
Anomaly						
Anomaly						

30x-60x Magnification

- a. improper substrate or bonding post plating material
- **b.** improper bond wire material or size
- c. metallic contamination or foreign material
- d. lifted or broken wires
- e. lifted, cracked or broken die/substrate
- **f.** improper die mounting
- g. excessive lead wire loop or sag
- **h.** improper bond technique and size
- i. improper assembly die location and orientation as compared to the applicable assembly drawing
- i. particles other than those introduce during opening

75x-150x Magnification

- **k.** metalization voids, corrosion, peeling, lifting, blistering or scratches
- **1.** bond inter-metallics extending radially more than 0.1 mil beyond the bond periphery in any direction
- m. improper die or substrate metalization design layout, topography or identification
- n. die cracks
- o. logo does not match
- **p.** die numbers do not match

DPA Component Counterfeit Checklist



Pass x Fail Check for bent, scratched, broken, or missing pins.

Comment:

Pass x Fail Check for corrosion or solder on pins.

Comment:

Pass x Fail Ensure that there are no scratches on the inside or outside of leads.

Comment:

Pass x Fail Verity that the pins are similar in gloss or shine, color, and texture.

Comment:

Pass x Fail Make sure the pins are not oxidized, tinned, or discolored.

Comment:

Pass x Fail Watch for leads that are too shiny for older date codes or too dull for new date codes.

Comment:

Pass x Fail Verify that dirt or other foreign substances are not on the parts or leads.

Comment:

Pass x Fail Ensure that there are not multiple countries of origins for identical date codes/lot codes.

Comment:

Pass x Fail Check for minor directional scratches, in other words, small abrasions that usually appear to be in one direction on the top of the parts.

Comment:

Pass x Fail Ensure that the surface of the parts have not been mechanically or otherwise resurfaced and re-stamped.

Comment:

Pass x Fail Confirm that there are not minor cracks on the surface of the parts.

Comment:

Pass x Fail Make sure that there are not colored dots or ink marks on the tops of the components which indicate previous testing or programming.

Comment:

Pass x Fail Make certain that "country of origin" circles/marks on the bottom of parts are consistent.

Comment:



Figure: 1

Magnification: 10x Subject: Front view

Subject: Back view

Top of chip de-capped for DPA

Magnification: 300x

Subject: inside of de-capped chip from Figure 1

name and logo is present.

Note* Images are clearly visible when viewed by microscope, but lower resolution in photo image.

